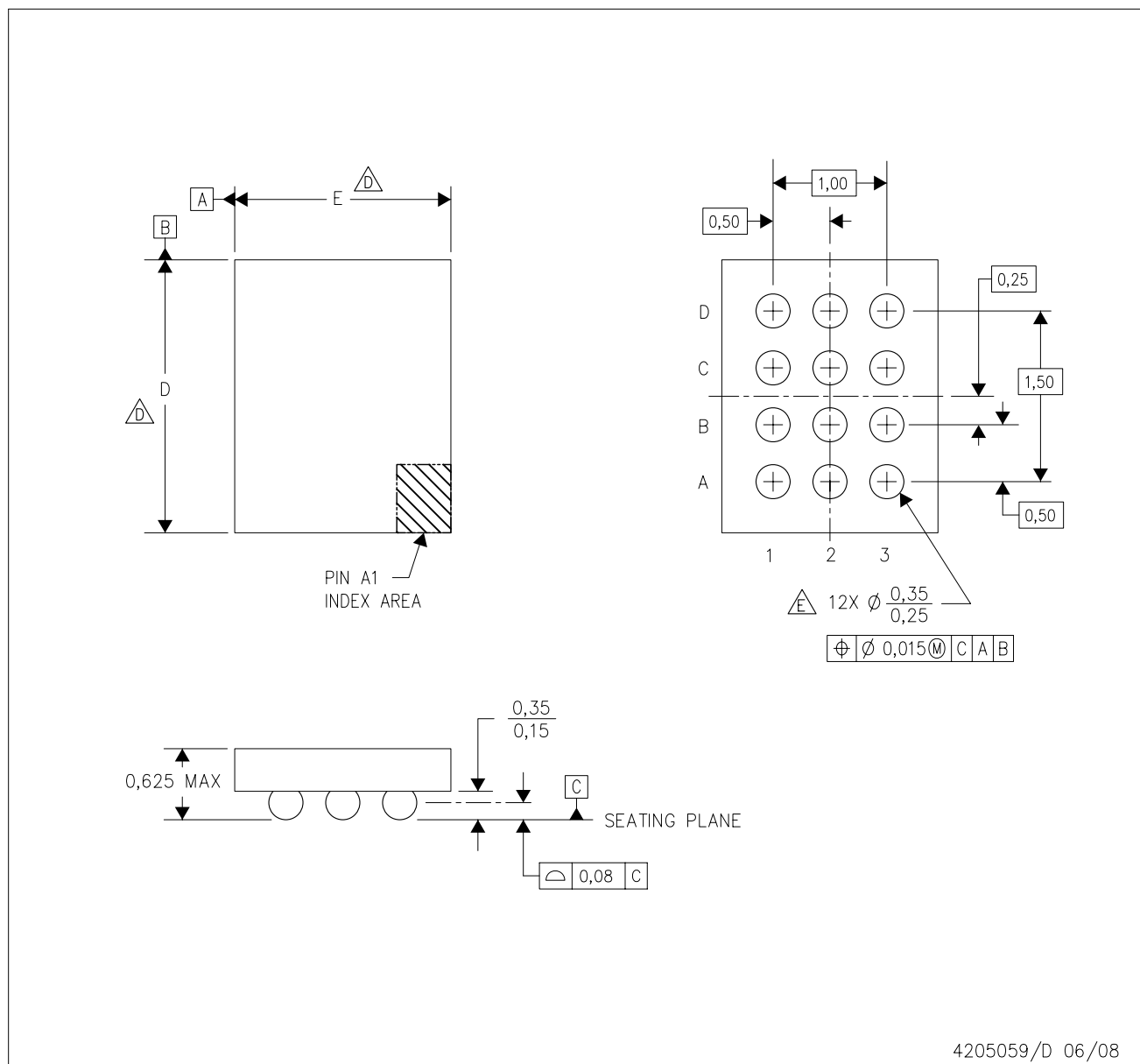


YZG (R-XBGA-N12)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoFree™ package configuration.
 - D. Devices in YZG package can have dimension D ranging from 1.94 to 2.65 mm and dimension E ranging from 1.44 to 2.15 mm. To determine the exact package size of a particular device, refer to the device datasheet or contact a local TI representative.
 - E. Reference Product Data Sheet for array population.
4 x 3 matrix pattern is shown for illustration only.
 - F. This package contains lead-free balls.
Refer to YEG (Drawing #4204182) for tin-lead (SnPb) balls.

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